ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN20950X
Issue Date: 26 October 2016

Title of Change:	Copper wire, mold compound conversion and Leadframe material change for LB1936V and LB1973JA.
Proposed first ship date:	2 February 2017 *or earlier upon customer approval.*
Contact information:	Contact your local ON Semiconductor Sales Office or < Tsutomu.Shimazaki@onsemi.com > < Takashi.Harashima@onsemi.com>< Takeshi2.Hoshino@onsemi.com><Kazumi.Onda@onsemi.com> < Shinya.Okada@onsemi.com>< Yoshiyuki.Nunokawa@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or < jun.hasunuma@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Satoru.Fujinuma@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☒ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable

☒ ON Semiconductor site(s) :
ON Tarlac City, Philippines
_____

☐ External Foundry/Subcon site(s)
_____

Description and Purpose:

This Final Notification announces the following changes for the list of affected devices:

- Affected devices will be identified with date code
- Gold wire connecting chip and Lead will be changed to Copper wire.
- Lead frame raw materials are changed.
- Mold resin will be changed for **LB1936V-TLM-E**, suitable for Copper wire.
- Mold resin for **LB1973JA** will not change.

Material to be changed for LB1936V-TLM-E	Before Change	After Change
Wire	Gold wire	Copper wire
Lead frame	LF-M16VX80D5-20-P	LF-M16VX80D5-94-P
Mold resin	ST8950CH	CV8210AN

Material to be changed for LB1973JA-AH	Before Change	After Change
Wire	Gold wire	Copper wire
Lead frame	LF-M16VX80D5-20-P	LF-M16VX80D5-94-P

There is no change of the electrical characteristic specifications with this changing.

Reliability Data Summary:

QV DEVICE NAME : LB1936V
PACKAGE : SSOP16(225mil)

Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Tj=Tjmax, Vcc=Operatingmax	1000 hrs	0/22
THB*	EIAJ ED-4701/100	85°C, 85% RH, Vcc=recommended	1000 hrs	0/22
TC*	EIAJ ED-4701/100	Ta= -65°C to +150°C	100 cyc	0/22
AC*	EIAJ ED-4701-3	Ta=121°C ,RH=100% ,205kPa	50 hrs	0/22
HTSL	EIAJ ED-4701/200	Ta= 150°C	1000 hrs	0/22
RSH	EIAJ ED-4701/300	Ta = 255°C , 10 sec (peak 260°C)	2times	0/22

Notes:
*The test items with * mark are put into operation after the reflow soldering (at 255℃ for 10seconds)*

Electrical Characteristic Summary:
There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LB1936V-TLM-E	LB1936V
LB1973JA-AH	